

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT6018925

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	POWERCHIP TECHNOLOGY CORPORATION	06/28/2019
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	POWERCHIP SEMICONDUCTOR MANUFACTURING CORPORATION	
<b>Street Address:</b>	NO. 18, LI-HSIN RD. 1, HSINCHU SCIENCE PARK,	
<b>City:</b>	HSINCHU	
<b>State/Country:</b>	TAIWAN	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	<b>Application Number:</b>	16373656
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(949)391-4699	
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<b>ATTORNEY DOCKET NUMBER:</b>	83899-US-PA	
<b>NAME OF SUBMITTER:</b>	BELINDA LEE	
<b>SIGNATURE:</b>	/Belinda Lee/	
<b>DATE SIGNED:</b>	03/16/2020	
<b>Total Attachments: 2</b>		
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## ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

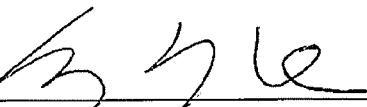
**Powerchip Technology Corporation** a corporation having a place of business at No. 12, Li-Hsin Rd. I, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereafter ASSIGNOR) has been assigned or otherwise has an ownership interest in certain new and useful improvements as set forth in the patents and patent applications listed in attached Appendix A.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, ASSIGNOR hereby:

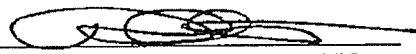
- 1) Sell(s), assign(s) and transfer(s) to **Powerchip Semiconductor Manufacturing Corporation**, a corporation having a place of business at No. 18, Li-Hsin Rd. I, Hsinchu Science Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as "ASSIGNEE") the entire right, title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed therein.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application(s) or any division(s), continuation(s), substitute(s), re-examination(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application(s), as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representative(s), and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that ASSIGNOR has not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signatures of Assignor and Assignee  
with the execution date of this Assignment indicated beside the signature(s).

Assignor (Conveying Party):

By:  Date: 2019.06.28  
Typed Name: STEVE CHEN  
Title: CHAIRMAN  
Company: **Powerchip Technology Corporation**  
No. 12, Li-Hsin Rd. I, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Assignee (Receiving Party):

By:  Date: 2019.06.28  
Typed Name: CHONG-JEN HUANG  
Title: CHAIRMAN  
Company: **Powerchip Semiconductor Manufacturing Corporation**  
No. 18, Li-Hsin Rd. I, Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

Appendix A

	<b>Title</b>	<b>Filing/ Issue Date</b>	<b>Serial/ Patent No.</b>	<b>Attorney Docket No.</b>
<b>1</b>	ION SOURCE HEAD STRUCTURE OF SEMICONDUCTOR ION IMPLANTER	16/373,656	2019/4/3	083899-US-PA (PT.AP-2036)